# **MOSFET** – Single P-Channel, Small Signal, XDFN3, 0.62 x 0.42 x 0.4 mm -20 V, -127 mA

• Low Profile Ultra Small Package, XDFN3 (0.62 x 0.42 x 0.4 mm)

• These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS



# **ON Semiconductor®**

## www.onsemi.com

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> MAX	I <sub>D</sub> Max
	5.0 Ω @ –4.5 V	
	5.5 Ω @ –3.3 V	
–20 V	6.0 Ω @ –2.5 V	–127 mA
	7.0 Ω @ –1.8 V	
	10 Ω @ –1.5 V	

### Applications

Compliant

• -1.5 V Gate Drive

Features

- Small Signal Load Switch
- High Speed Interfacing
- Level Shift

### **MAXIMUM RATINGS** ( $T_J = 25^{\circ}C$ unless otherwise stated)

for Extremely Space-Constrained Applications

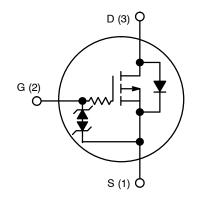
(,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,					
Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V <sub>DSS</sub>	20	V
Gate-to-Source Voltage			V <sub>GS</sub>	±8	V
Continuous Drain	Steady	$T_A = 25^{\circ}C$	Ι <sub>D</sub>	-127	mA
Current (Note 1)	State	$T_A = 85^{\circ}C$		-91	
	t ≤ 5 s	$T_A = 25^{\circ}C$		-146	
Power Dissipation (Note 1)	Steady State	$T_A = 25^{\circ}C$	PD	125	mW
	t ≤ 5 s			166	
Pulsed Drain Current	t <sub>p</sub> = 10 μs		I <sub>DM</sub>	-488	mA
Operating Junction and Storage Temperature		T <sub>J</sub> , T <sub>STG</sub>	–55 to 150	°C	
Source Current (Body Diode) (Note 2)			۱ <sub>S</sub>	200	mA
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)		ΤL	260	°C	
0			Dell's secondate		

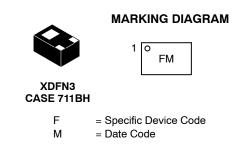
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Surface-mounted on FR4 board using the minimum recommended pad size, or 2 mm<sup>2</sup>, 1 oz Cu.

2. Pulse Test: pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2%

### **P-CHANNEL MOSFET**





## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NTNS5K0P021ZTCG	XDFN3 (Pb-Free)	8000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

## THERMAL RESISTANCE RATINGS

Parameter	Symbol	Мах	Unit	
Junction-to-Ambient - Steady State (Note 3)	$R_{\thetaJA}$	998	°C/W	
Junction-to-Ambient – t $\leq$ 5 s (Note 3)	$R_{\thetaJA}$	751	C/VV	

3. Surface-mounted on FR4 board using the minimum recommended pad size, or 2 mm<sup>2</sup>, 1 oz Cu.

## **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = $25^{\circ}$ C unless otherwise stated)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = -25 \text{ V}$	i0 μA	-20			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS}$ = 0 V, $V_{DS}$ = -5 V	$T_J = 25^{\circ}C$			-50	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 V, V_{DS} = -16 V$ $T_{J} = 25^{\circ}C$				-100	nA
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{DS}$ = 0 V, $V_{GS}$ = ±5 V				±100	nA
ON CHARACTERISTICS (Note 4)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_D = -2$	50 μA	-0.4		-1.0	V
Drain-to-Source On Resistance		$V_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -100 \text{ mA}$			2.1	5.0	Ω
	R <sub>DS(on)</sub>	V <sub>GS</sub> = -3.3 V, I <sub>D</sub> = -100 mA			2.4	5.5	
		$V_{GS} = -2.5 \text{ V}, I_D = -50 \text{ mA}$			2.7	6.0	
		$V_{GS} = -1.8 \text{ V}, I_D = -20 \text{ mA}$			3.6	7.0	
		V <sub>GS</sub> = -1.5 V, I <sub>D</sub> = -10 mA			4.2	10	
Forward Transconductance	<b>g</b> fs	$V_{DS} = -5 \text{ V}, \text{ I}_{D} = -125 \text{ mA}$			0.35		S
Source-Drain Diode Voltage	V <sub>SD</sub>	$V_{GS} = 0 \text{ V}, \text{ I}_{S} = -10 \text{ mA}$			-0.6	-1.0	V
CHARGES & CAPACITANCES							
Input Capacitance	C <sub>ISS</sub>				12.8		
Output Capacitance	C <sub>OSS</sub>	$V_{GS}$ = 0 V, freq = 1 MHz, $V_{DS}$ = –15 V			2.8		pF
Reverse Transfer Capacitance	C <sub>RSS</sub>				2.0		
SWITCHING CHARACTERISTICS, VG	S = 4.5 V (Not	e 4)					
Turn-On Delay Time	t <sub>d(ON)</sub>				37		
Rise Time	t <sub>r</sub>	- V <sub>GS</sub> = -4.5 V. V <sub>DD</sub> = -15 V.			71		_
Turn-Off Delay Time	t <sub>d(OFF)</sub>	$V_{GS}$ = -4.5 V, $V_{DD}$ = -15 V, $I_D$ = 200 mA, $R_G$ = 2 $\Omega$			280		ns

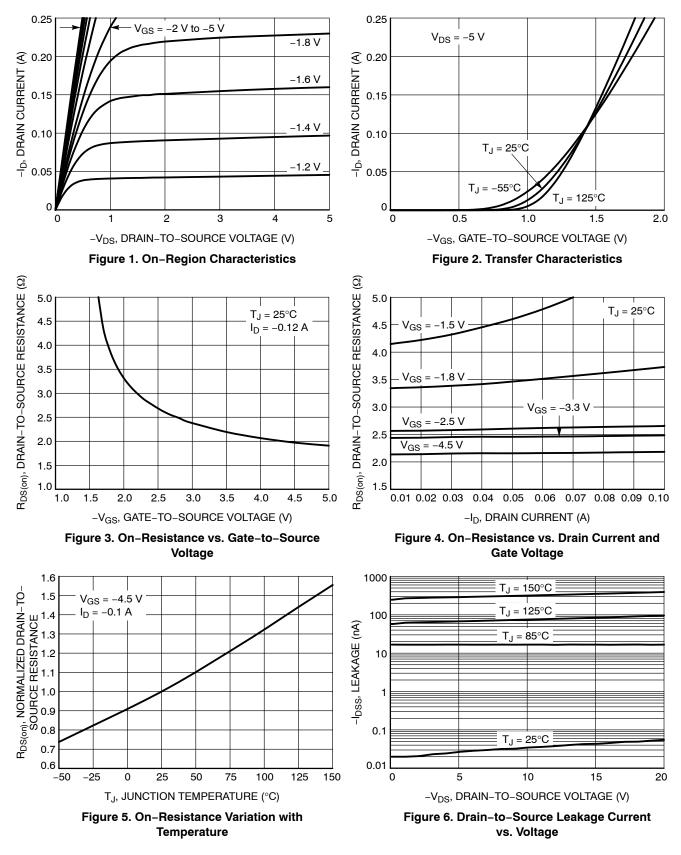
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4. Switching characteristics are independent of operating junction temperatures.

t<sub>f</sub>

Fall Time

## **TYPICAL CHARACTERISTICS**



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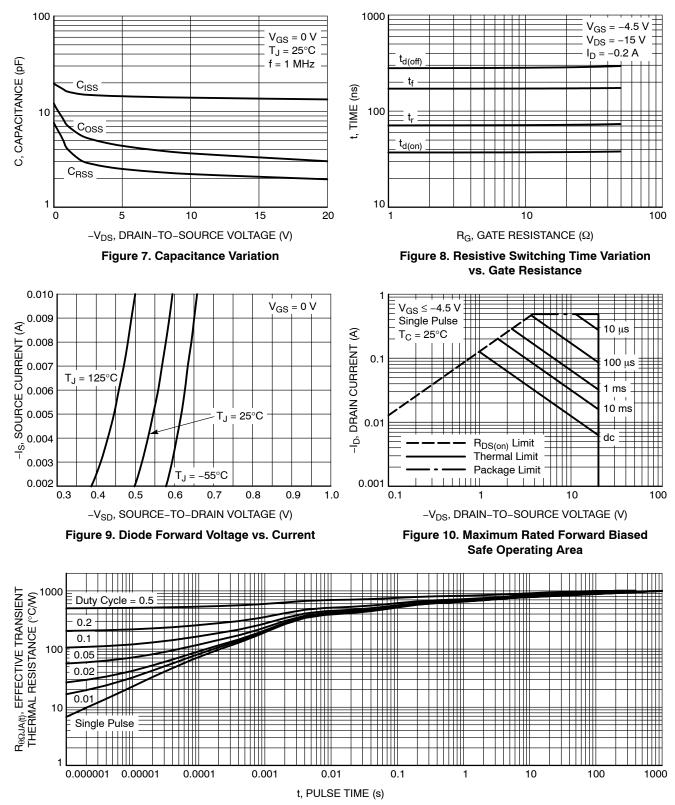
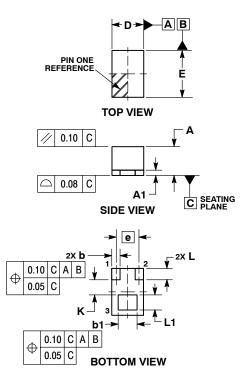


Figure 11. Thermal Response

### PACKAGE DIMENSIONS

XDFN3 0.42x0.62, 0.3P CASE 711BH **ISSUE O** 

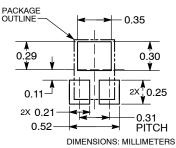


NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2 CONTROLLING DIMENSION: MILLIMETERS. 3. DIMENSION 6 AND 61 APPLIES TO THE PLATED TERMINALS AND IS MEASURED BETWEEN 0.20 AND 0.25MM FROM THE TERMINAL TIP.
- 4.
- COPLANARITY APPLIES TO THE PLATED TERMI-NALS

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.33	0.38	0.43	
A1			0.07	
b	0.05	0.11	0.17	
b1	0.20	0.25	0.30	
D	0.32	0.42	0.52	
Е	0.52	0.62	0.72	
е	0.30 BSC			
L	0.09	0.15	0.21	
L1	0.15	0.20	0.25	
K	0.20 REF			

#### RECOMMENDED SOLDER FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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